

Title (en)
PLATING DEVICE

Title (de)
ABSCHIEDUNGSVERFAHREN

Title (fr)
DISPOSITIF D'ELECTRODEPOSITION

Publication
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Application
EP 03765327 A 20030718

Priority
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Abstract (en)
[origin: US2004262150A1] A plating apparatus according to the present invention has a plating tank (40) for holding a plating solution (10), an anode (56) disposed so as to be immersed in the plating solution (10) in the plating tank (40), a regulation plate (60) disposed between the anode (56) and a plating workpiece (W) disposed so as to face the anode (56), and a plating power supply (24) for supply a current between the anode (56) and the plating workpiece (W) to carry out plating. The regulation plate (60) is disposed so as to separate the plating solution (10) held in the plating tank (40) into a plating solution on the anode side and a plating solution on the plating workpiece side, and a through-hole group (68) having a large number of through-holes (66) is formed in the regulation plate (60).

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IPC 8 full level
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• [X] JP 2002054000 A 20020219 - NITTO DENKO CORP
• [X] JP S63176500 A 19880720 - SHINKO ELECTRIC IND CO
• [E] US 2003155231 A1 20030821 - WENG CHAO-FU [TW]
• [X] DATABASE WPI Week 200231, Derwent World Patents Index; AN 2002-262527, XP002464511
• See references of WO 2004009879A1

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US 2004262150 A1 20041230; CN 100439571 C 20081203; CN 101387004 A 20090318; CN 101387004 B 20101215;
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